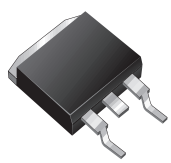
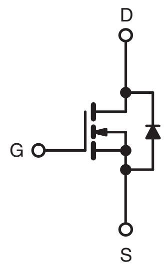
Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	100	
$R_{DS(on)}$ (Ω)	V_{GS} = 5 V	0.077
Q_g (Max.) (nC)	64	
Q_{gs} (nC)	9.4	
Q_{gd} (nC)	27	
Configuration	Single	

SMD-220





N-Channel MOSFET

FEATURES

- Surface Mount
- Available in Tape and Reel
- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- Logic-Level Gate Drive
- $R_{DS(on)}$ Specified at V_{GS} = 4 V and 5 V
- 175 °C Operating Temperature
- Lead (Pb)-free Available

Pb Available

RoHS* COMPLIANT

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The SMD-220 is a surface mount power package capable of accommodating die size up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The SMD-220 is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0 W in a typical surface mount application.

ORDERING INFORMATION		
Package	SMD-220	SMD-220
Lead (Pb)-free	IRL540SPbF	IRL540STRLPbF[a]
	SiHL540S-E3	SiHL540STL-E3[a]
SnPb	IRL540S	IRL540STRL[a]
	SiHL540S	SiHL540STL[a]

Note

a. See device orientation.

ABSOLUTE MAXIMUM RATINGS T_C = 25 °C, unless otherwise noted

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	100	V
Gate-Source Voltage			V_{GS}	± 10	
Continuous Drain Current	V_{GS} at 5 V	T_C = 25 °C	I_D	28	A
		T_C = 100 °C		20	
Pulsed Drain Current[a]			I_{DM}	110	
Linear Derating Factor				1.0	W/°C
Linear Derating Factor (PCB Mount)[e]				0.025	
Single Pulse Avalanche Energy[b]			E_{AS}	440	mJ
Avalanche Current[a]			I_{AR}	28	A
Repetiitive Avalanche Energy[a]			E_{AR}	15	mJ
Maximum Power Dissipation		T_C = 25 °C	P_D	150	W
Maximum Power Dissipation (PCB Mount)[e]		T_A = 25 °C		3.7	
Peak Diode Recovery dV/dt[c]			dV/dt	5.5	V/ns
Operating Junction and Storage Temperature Range			T_J, T_{stg}	- 55 to + 175	°C
Soldering Recommendations (Peak Temperature)		for 10 s		300[d]	

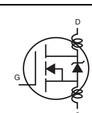
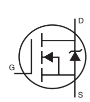
Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. V_{DD} = 25 V, starting T_J = 25 °C, L = 841 µH, R_G = 25 Ω, I_{AS} = 28 A (see fig. 12).
c. $I_{SD} \leq$ 28 A, dI/dt ≤ 170 A/µs, $V_{DD} \leq V_{DS}$, $T_J \leq$ 175 °C.
d. 1.6 mm from case.
e. When mounted on 1" square PCB (FR-4 or G-10 material).

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	62	°C/W
Maximum Junction-to-Ambient (PCB Mount)[a]	R_{thJA}	-	40	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	1.0	

Note
a. When mounted on 1" square PCB (FR-4 or G-10 material).

SPECIFICATIONS T_J = 25 °C, unless otherwise noted						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 µA	100	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = 1 mA	-	0.12	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	1.0	-	2.0	V
Gate-Source Leakage	I_{GSS}	V_{GS} = ± 10 V	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 100 V, V_{GS} = 0 V	-	-	25	µA
		V_{DS} = 80 V, V_{GS} = 0 V, T_J = 150 °C	-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	V_{GS} = 5 V, I_D = 17 A[b]	-	-	0.077	Ω
		V_{GS} = 4 V, I_D = 14 A[b]	-	-	0.11	
Forward Transconductance	g_{fs}	V_{DS} = 50 V, I_D = 17 A[b]	12	-	-	S
Dynamic						
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 25 V, f = 1.0 MHz, see fig. 5	-	2200	-	pF
Output Capacitance	C_{oss}		-	560	-	
Reverse Transfer Capacitance	C_{rss}		-	140	-	
Total Gate Charge	Q_g	V_{GS} = 5 V, I_D = 28 A, V_{DS} = 80 V, see fig. 6 and 13[b]	-	-	64	nC
Gate-Source Charge	Q_{gs}		-	-	9.4	
Gate-Drain Charge	Q_{gd}		-	-	27	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 50 V, I_D = 28 A, R_G = 9.0 Ω, R_D = 1.7 Ω, see fig. 10[b]	-	8.5	-	ns
Rise Time	t_r		-	170	-	
Turn-Off Delay Time	$t_{d(off)}$		-	35	-	
Fall Time	t_f		-	80	-	
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact 	-	4.5	-	nH
Internal Source Inductance	L_S		-	7.5	-	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	28	A
Pulsed Diode Forward Current[a]	I_{SM}		-	-	110	
Body Diode Voltage	V_{SD}	T_J = 25 °C, I_S = 28 A, V_{GS} = 0 V[b]	-	-	2.5	V
Body Diode Reverse Recovery Time	t_{rr}	T_J = 25 °C, I_F = 28 A, dI/dt = 100 A/µs[b]	-	200	260	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	1.7	2.9	µC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

Notes
a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Pulse width ≤ 300 µs; duty cycle ≤ 2 %.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

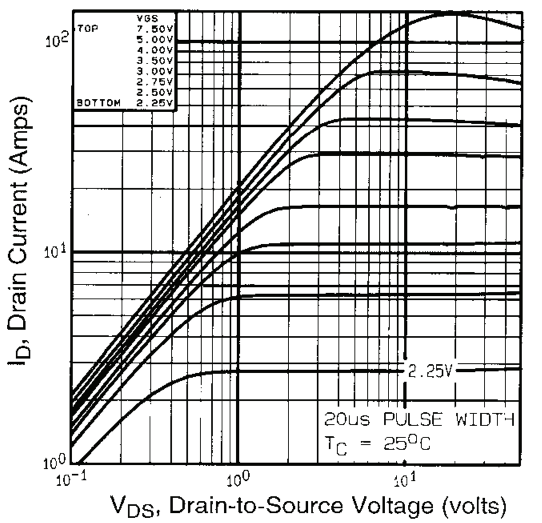


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

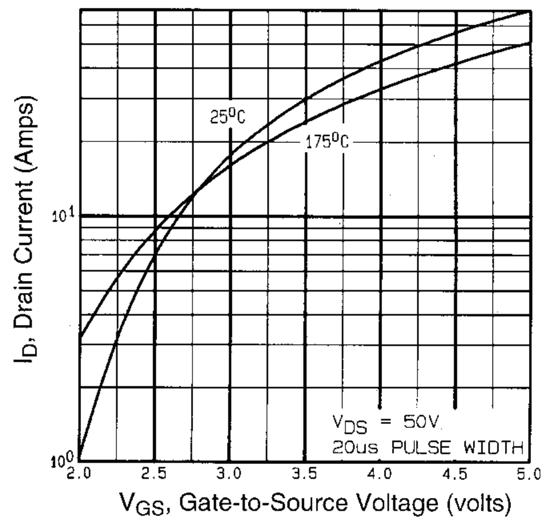


Fig. 3 - Typical Transfer Characteristics

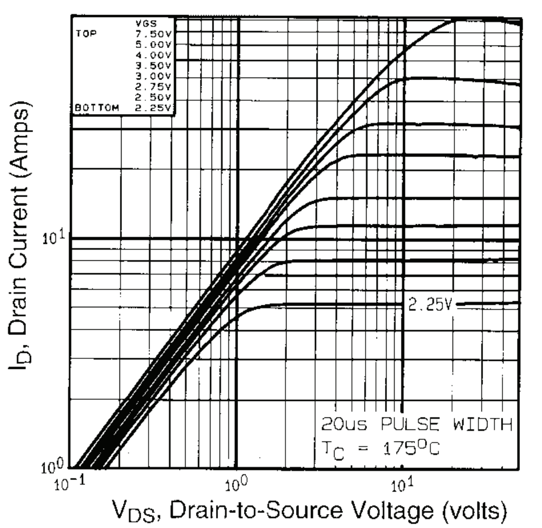


Fig. 2 - Typical Output Characteristics, T_C = 175 °C

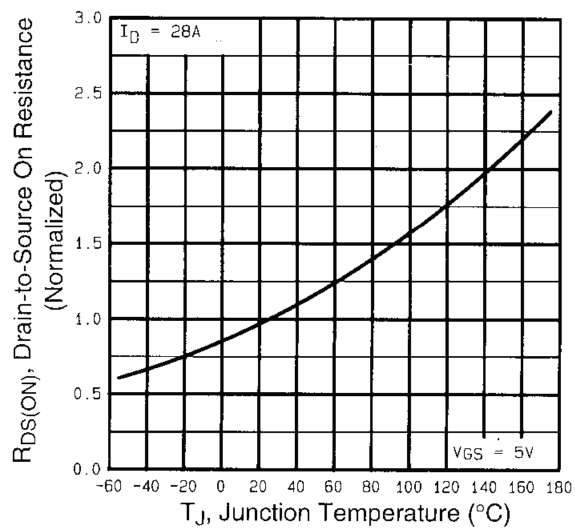


Fig. 4 - Normalized On-Resistance vs. Temperature

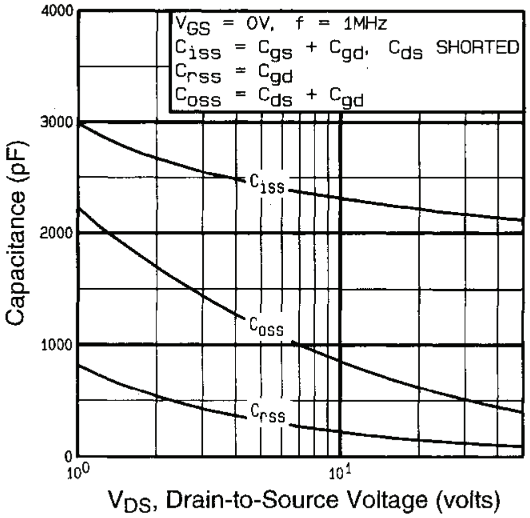


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

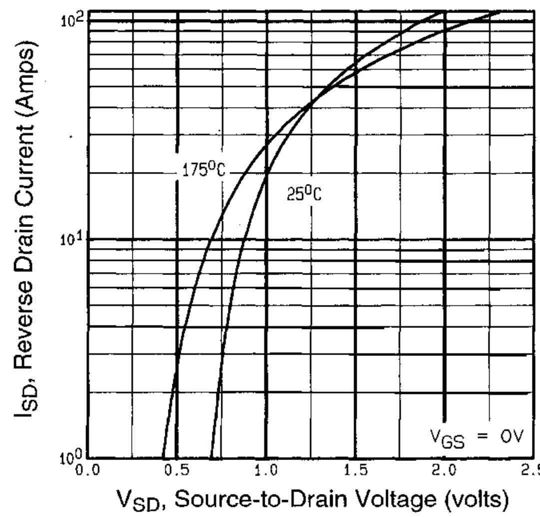


Fig. 7 - Typical Source-Drain Diode Forward Voltage

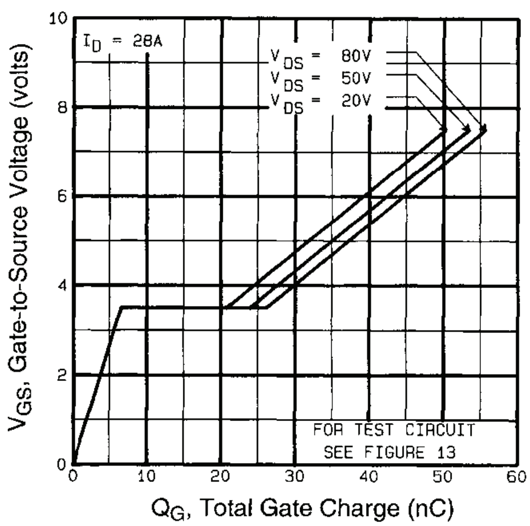


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

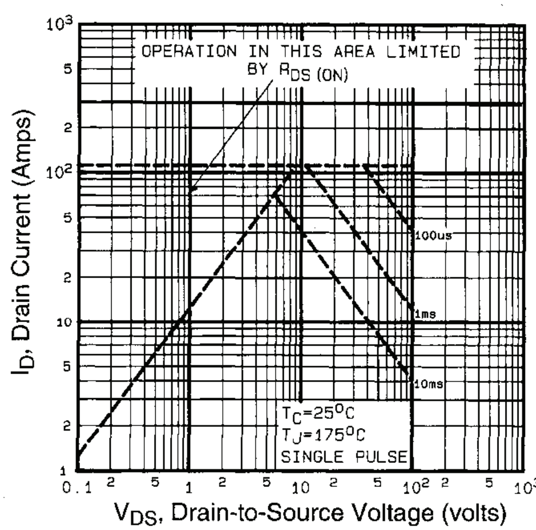


Fig. 8 - Maximum Safe Operating Area

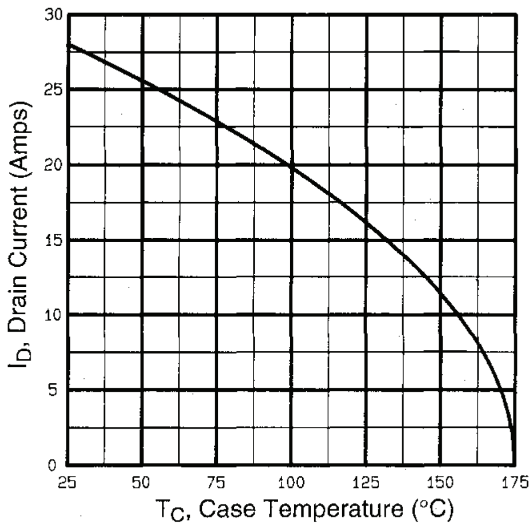


Fig. 9 - Maximum Drain Current vs. Case Temperature

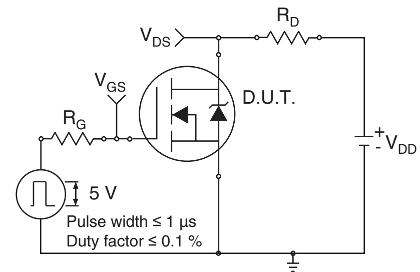


Fig. 10a - Switching Time Test Circuit

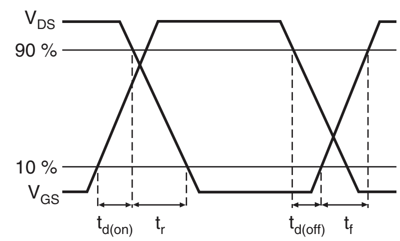


Fig. 10b - Switching Time Waveforms

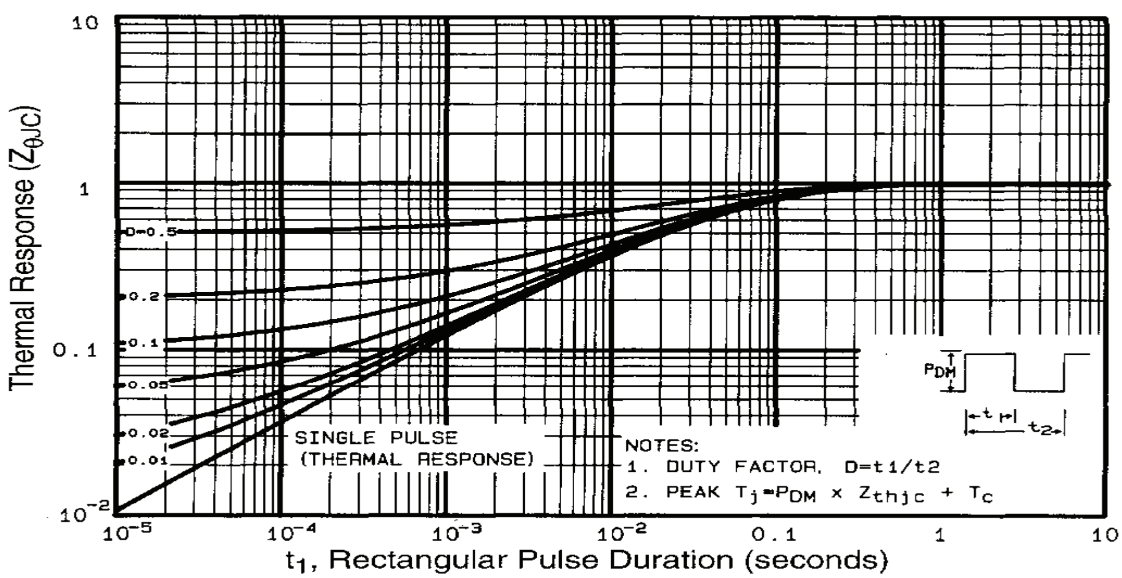


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

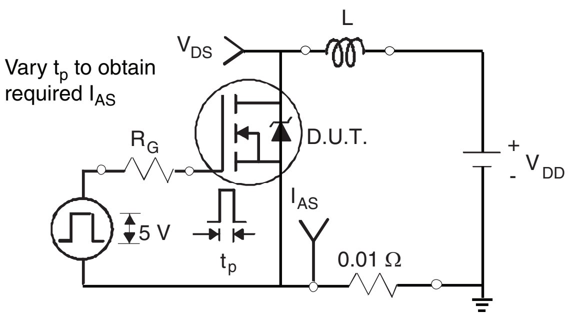


Fig. 12a - Unclamped Inductive Test Circuit

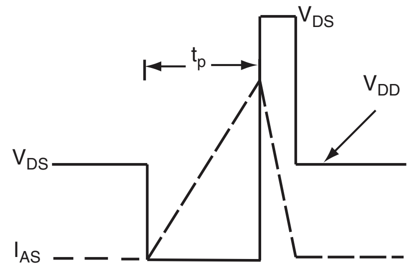


Fig. 12b - Unclamped Inductive Waveforms

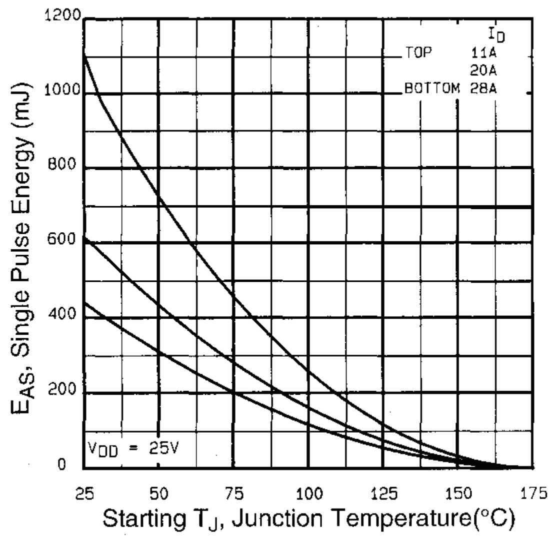


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

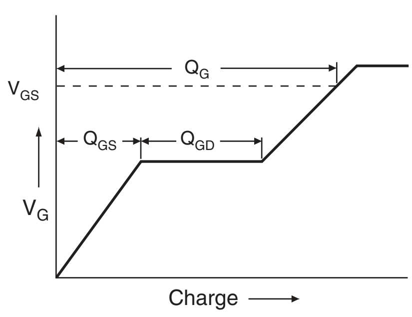


Fig. 13a - Basic Gate Charge Waveform

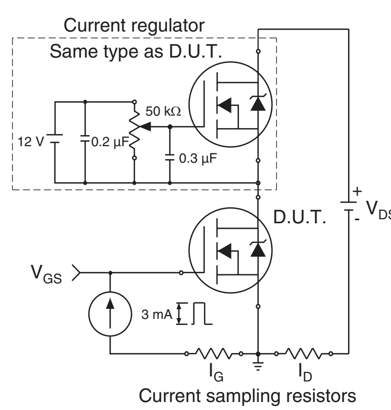
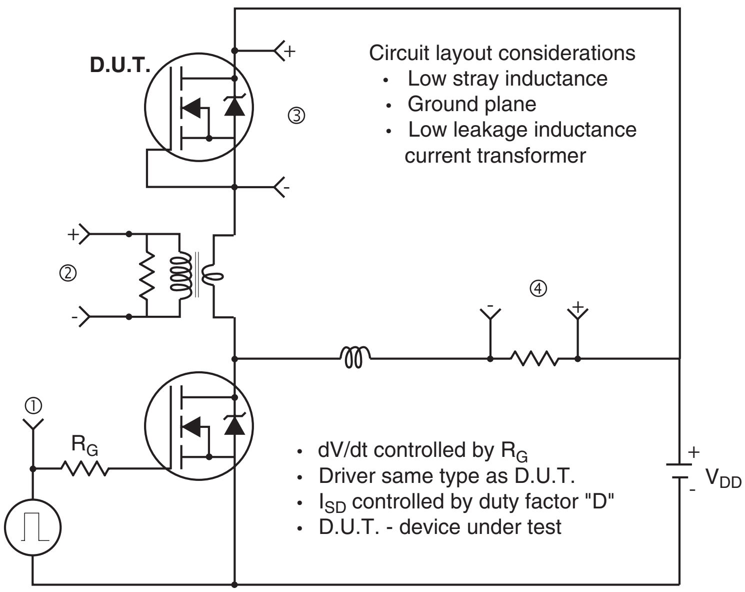
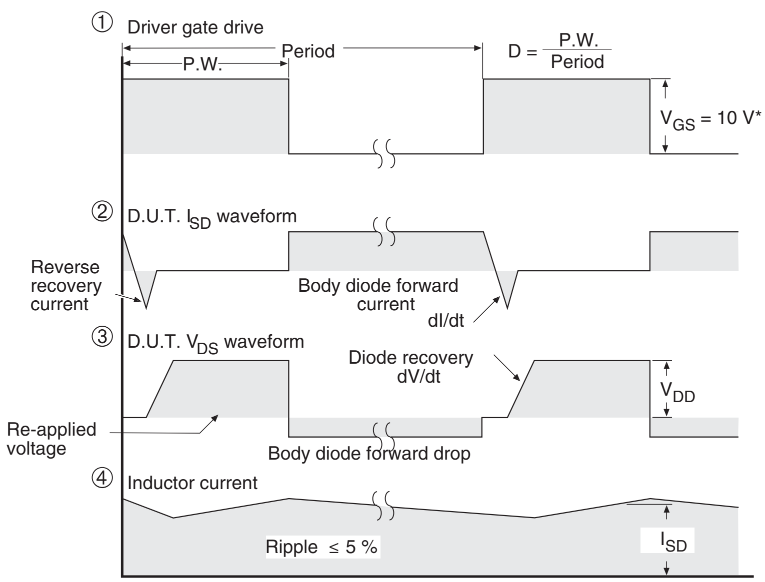


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit





* V_{GS} = 5 V for logic level devices

Fig. 14 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?90386.

Disclaimer

All product specifications and data are subject to change without notice.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, “Vishay”), disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

Vishay disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Vishay’s terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications unless otherwise expressly indicated. Customers using or selling Vishay products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Vishay for any damages arising or resulting from such use or sale. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

Product names and markings noted herein may be trademarks of their respective owners.